

DATASHEET

ITR1504SR10A/TR

Features

- High sensitivity
- Cut-Off visible wavelength
- Compliance Halogen Free(Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)
- Compliance with EU REACH
- This product itself will remain within RoHS compliant version.



Description

The SMD type ITR1504SR10A/TR consists of an infrared emitting diode and an silicon phototransistor. The phototransistor receives radiation from the IR only. This is the normal situation. But when a reflecting object close to ITR, phototransistor receives the reflecting radiation and the different distance have different light current.

Applications

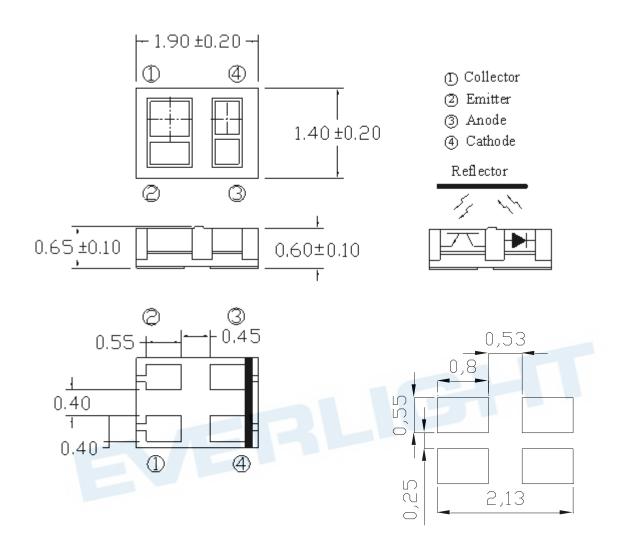
- Printer
- Switch Scanner
- Non-contact Switching

Device Selection Guide

Device No.	Chip Material	Lens Color		
IR	GaAs	Black clear		
PT	Silicon	Black clear		



Package Dimensions



Recommended Soldering Pattern

Notes:

- 1. All dimensions are in millimeters
- 2. Tolerances unless dimensions ±0.2mm
- 3. Lead spacing is measured where the lead emerge from the package



Absolute Maximum Ratings (Ta=25°C)

Parameter		Ratings	Unit
Power Dissipation at(or below) 25°C Free Air Temperature	Pd	75	mW
Reverse Voltage	V_R	6	V
Forward Current	I_{F}	50	mA
Collector Power Dissipation	$P_{\rm C}$	75	mW
Collector Current	$I_{\rm C}$	20	mA
Collector-Emitter Voltage	B V _{CEO}	30	V
Emitter-Collector Voltage	B V _{ECO}	5	V
emperature	Topr	-25~+85	$^{\circ}\mathbb{C}$
Storage Temperature		-40~+100	$^{\circ}\mathbb{C}$
Lead Soldering Temperature (*1)		260	$^{\circ}\mathbb{C}$
	Power Dissipation at(or below) 25°C Free Air Temperature Reverse Voltage Forward Current Collector Power Dissipation Collector Current Collector-Emitter Voltage Emitter-Collector Voltage emperature perature	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

^(*1) t ≤ 5 Sec

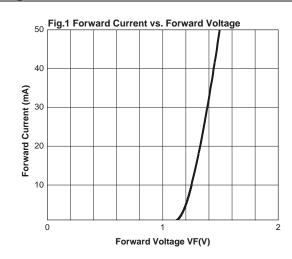
Electro-Optical Characteristics (Ta=25°C)

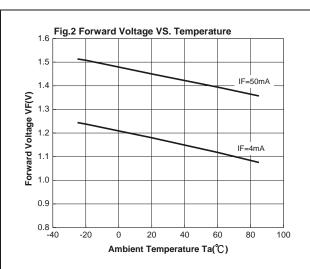
Parameter		Symbol	Min.	Тур.	Max.	Unit	Condition	
Input	Forward Voltage	V_{F}	-	1.25	1.5	V	I _F =4mA	
	Reverse Current	I_R	-	-	10	μΑ	V _R =6V	
	Peak Wavelength	$\lambda_{ m P}$	-	940	-	nm	I _F =20mA	
Output	Dark Current	I_{CEO}		1	0.1	uA	V _{CE} =10V	
Transfer Characteristics	Collect Current	$I_{C(ON)}$	60	T.	550	μΑ	V_{CE} =2V, I_F =4mA	
	Operating Dark Current*	I_{CEOD}			1	μΑ	V_{CE} =2V, I_{F} =2mA	
	Rise Time	T_{r}	-	15	-	μs	$\begin{array}{c} V_{\text{CE}}{=}2V \\ I_{\text{C}}{=}0.1\text{mA} \\ R_{\text{L}}{=}1000\Omega \end{array}$	
	Fall Time	$\mathrm{T_{f}}$	-	15	-	μs		

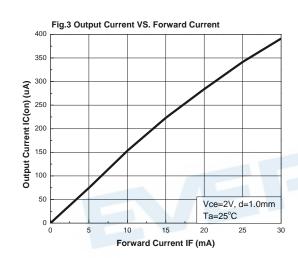
^{*}Operating dark current may be affected by surrounding situation.

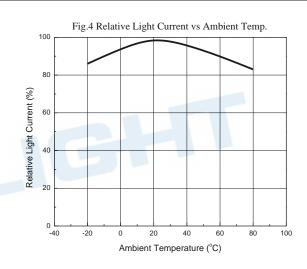


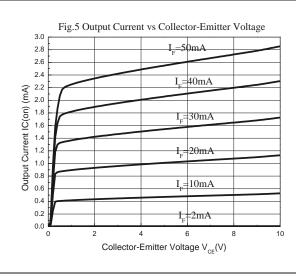
Opto Characteristic Curves

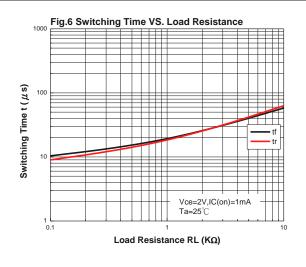




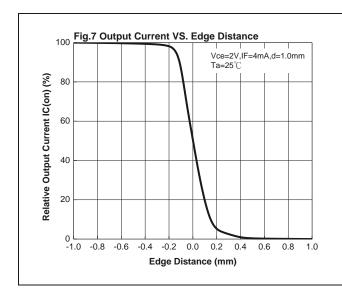


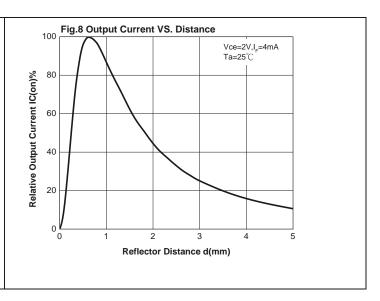




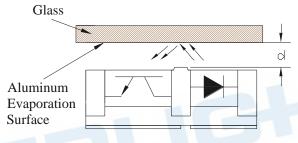




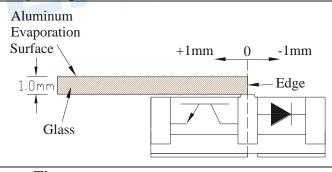




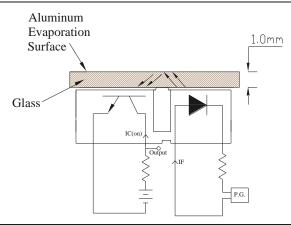
Measuring Specification For Reflector Response

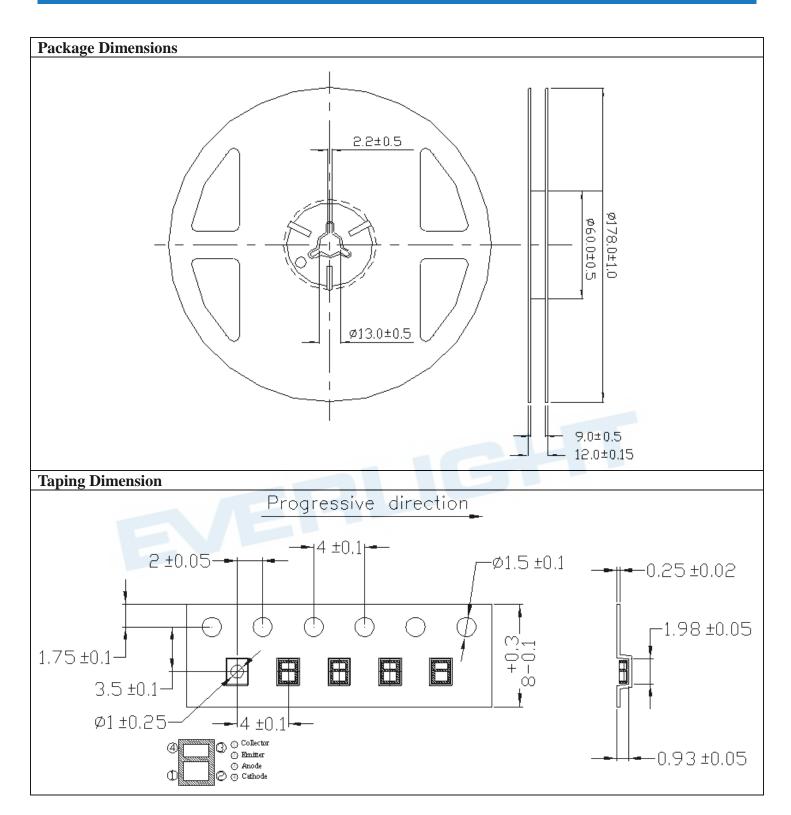


Measuring Specification For Edge Response



Measuring Circuit For Response Time



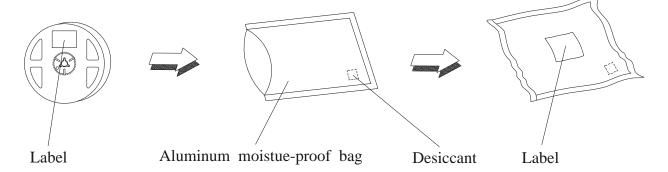


Packing Quantity Specification

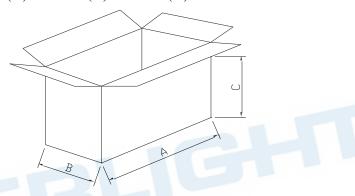
 $1.2000PCS/1Bag \cdot 10Bags/1Box$

2.10Boxes/1Carton

Packing Procedure



Outer Carton Dimension: 409mm(A)*245mm(B)*360mm(C)



Recommended Method of Storage

The following are general recommendations for moisture sensitive level (MSL) 3 storage and use :

- 1. Storage
- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the device should be kept at 30° C or less and 90%RH or less.
- 1.3 The device should be used within a year.
- 1.4 After opening the package, the device should be kept at 30°C or less and 70%RH or less.
- 1.5 The device should be used within 168 hours (7 days) after opening the package.
- 1.6 If the moisture absorbent material (silica gel) has faded away or the device have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

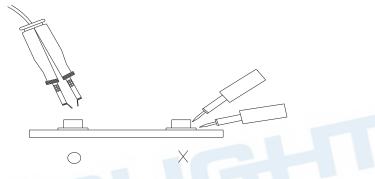
2. Soldering Condition

- a) Pb-free solder temperature profile
- b) Reflow soldering should not be done more than two times.
- c) When soldering, do not put stress on the LEDs during heating.
- d) After soldering, do not warp the circuit board.

Pre-heating $1 \sim 5^{\circ}\text{C/sec.}$ Pre-heating $180 \sim 200^{\circ}\text{C}$ 60sec.Max.Above 220°C less. leating. 120sec.Max.

Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

- Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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